

# NL27WZ16

## Dual Buffer

The NL27WZ16 is a high performance dual buffer operating from a 1.65 to 5.5 V supply. At  $V_{CC} = 3\text{ V}$ , high impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance.

- Extremely High Speed:  $t_{PD} = 2.0\text{ ns}$  (typical) at  $V_{CC} = 5.0\text{ V}$
- Designed for 1.65 V to 5.5 V  $V_{CC}$  Operation
- Over Voltage Tolerant Inputs
- LVTTL Compatible – Interface Capability With 5.0 V TTL Logic with  $V_{CC} = 3.0\text{ V}$
- LVC MOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Chip Complexity: FET = 72; Equivalent Gate = 18

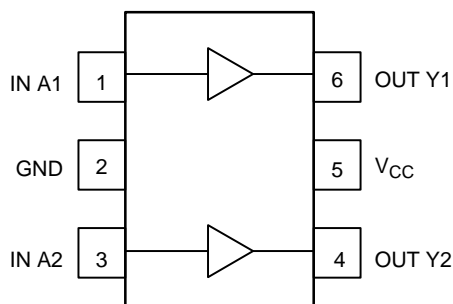


Figure 1. Pinout (Top View)

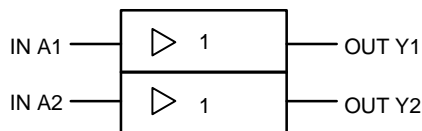


Figure 2. Logic Symbol

### PIN ASSIGNMENT

1	IN A1
2	GND
3	IN A2
4	OUT Y2
5	$V_{CC}$
6	OUT Y1

### FUNCTION TABLE

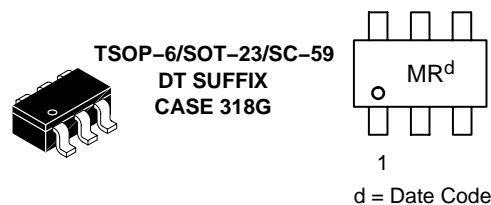
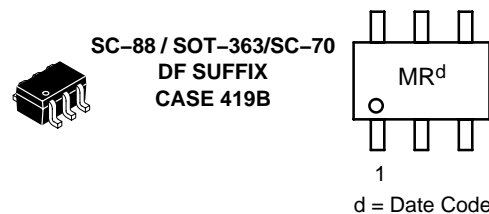
A Input	$\bar{Y}$ Output
L	L
H	H



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### MARKING DIAGRAMS



### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

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## MAXIMUM RATINGS (Note 1)

Symbol	Characteristics	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0	V
V <sub>I</sub>	DC Input Voltage	-0.5 ≤ V <sub>I</sub> ≤ +7.0	V
V <sub>O</sub>	DC Output Voltage Output in Z or LOW State (Note 2)	-0.5 ≤ V <sub>O</sub> ≤ 7.0	V
I <sub>IK</sub>	DC Input Diode Current V <sub>I</sub> < GND	-50	mA
I <sub>OK</sub>	DC Output Diode Current V <sub>O</sub> < GND	-50	mA
I <sub>O</sub>	DC Output Sink Current	±50	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	±100	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin	±100	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C
P <sub>D</sub>	Power Dissipation in Still Air SC-88, TSOP-6	200	mW
θ <sub>JA</sub>	Thermal Resistance SC-88, TSOP-6	333	°C/W
T <sub>L</sub>	Lead Temperature, 1 mm from case for 10 s	260	°C
T <sub>J</sub>	Junction Temperature under Bias	+150	°C
V <sub>ESD</sub>	ESD Withstand Voltage Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 N/A	V
I <sub>Latch-Up</sub>	Latch-Up Performance Above V <sub>CC</sub> and Below GND at 85°C (Note 6)	±500	mA

1. Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute-maximum-rated conditions is not implied.
2. I<sub>O</sub> absolute maximum rating must be observed.
3. Tested to EIA/JESD22-A114-A
4. Tested to EIA/JESD22-A115-A
5. Tested to JESD22-C101-A
6. Tested to EIA/JESD78

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage Operating Data Retention Only	1.65 1.5	5.5 5.5	V
V <sub>I</sub>	Input Voltage	0	5.5	V
V <sub>O</sub>	Output Voltage (High or LOW State)	0	5.5	V
T <sub>A</sub>	Operating Free-Air Temperature	-40	+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate V <sub>CC</sub> = 1.8 V ± 0.15 V V <sub>CC</sub> = 2.5 V ± 0.2 V V <sub>CC</sub> = 3.0 V ± 0.3 V V <sub>CC</sub> = 5.0 V ± 0.5 V	0 0 0 0	20 20 10 5	ns/V

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## DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C			-40°C ≤ T <sub>A</sub> ≤ 85°C		Unit	Condition
			Min	Typ	Max	Min	Max		
V <sub>IH</sub>	High-Level Input Voltage	1.65 to 1.95 2.3 to 5.5	0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>			0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>		V	
V <sub>IL</sub>	Low-Level Input Voltage	1.65 to 1.95 2.3 to 5.5			0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>		0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>	V	
V <sub>OH</sub>	High-Level Output Voltage V <sub>IN</sub> = V <sub>IH</sub>	1.65 1.8 2.3 3.0 4.5	1.55 1.7 2.2 2.9 4.4	1.65 1.8 2.3 3.0 4.5		1.55 1.7 2.2 2.9 4.4		V	I <sub>OH</sub> = -100 μA
		1.65 2.3 3.0 3.0 4.5	1.29 1.9 2.4 2.3 3.8	1.52 2.15 2.80 2.68 4.20		1.29 1.9 2.4 2.3 3.8		V	I <sub>OH</sub> = -4 mA I <sub>OH</sub> = -8 mA I <sub>OH</sub> = -16 mA I <sub>OH</sub> = -24 mA I <sub>OH</sub> = -32 mA
V <sub>OL</sub>	Low-Level Output Voltage V <sub>IN</sub> = V <sub>IL</sub>	1.65 1.8 2.3 3.0 4.5		0.0 0.0 0.0 0.0 0.0	0.1 0.1 0.1 0.1 0.1		0.1 0.1 0.1 0.1 0.1	V	I <sub>OL</sub> = 100 μA
		1.65 2.3 3.0 3.0 4.5		0.08 0.10 0.15 0.22 0.22	0.24 0.30 0.40 0.55 0.55		0.24 0.30 0.40 0.55 0.55	V	I <sub>OL</sub> = 4 mA I <sub>OL</sub> = 8 mA I <sub>OL</sub> = 16 mA I <sub>OL</sub> = 24 mA I <sub>OL</sub> = 32 mA
I <sub>IN</sub>	Input Leakage Current	0 to 5.5			±1.0		±1.0	μA	0 V ≤ V <sub>IN</sub> ≤ 5.5 V
I <sub>OFF</sub>	Power Off Leakage Current	0.0			1.0		10	μA	V <sub>IN</sub> or V <sub>OUT</sub> = 5.5 V
I <sub>CC</sub>	Quiescent Supply Current	1.65 to 5.5			1.0		10	μA	V <sub>IN</sub> = 5.5 V, GND

## AC ELECTRICAL CHARACTERISTICS t<sub>R</sub> = t<sub>F</sub> = 2.5 ns; C<sub>L</sub> = 50 pF; R<sub>L</sub> = 500 Ω

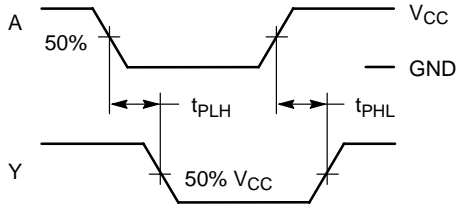
Symbol	Parameter	Condition	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C			-40°C ≤ T <sub>A</sub> ≤ 85°C		Unit
				Min	Typ	Max	Min	Max	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay (Figure 3 and 4)	R <sub>L</sub> = 1 MΩ, C <sub>L</sub> = 15 pF	1.8 ± 0.15	1.8	8.0	9.6	1.8	10.2	ns
		R <sub>L</sub> = 1 MΩ, C <sub>L</sub> = 15 pF	2.5 ± 0.2	1.0	3.0	5.2	1.0	5.8	
		R <sub>L</sub> = 1 MΩ, C <sub>L</sub> = 15 pF	3.3 ± 0.3	0.8	2.3	3.6	0.8	4.0	
		R <sub>L</sub> = 500 Ω, C <sub>L</sub> = 50 pF		1.2	3.0	4.6	1.2	5.1	
		R <sub>L</sub> = 1 MΩ, C <sub>L</sub> = 15 pF	5.0 ± 0.5	0.5	1.8	2.9	0.5	3.2	
		R <sub>L</sub> = 500 Ω, C <sub>L</sub> = 50 pF		0.8	2.4	3.8	0.8	4.2	

## CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	7.0	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 7)	10 MHz, V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub> 10 MHz, V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	9 11	pF

7. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no-load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

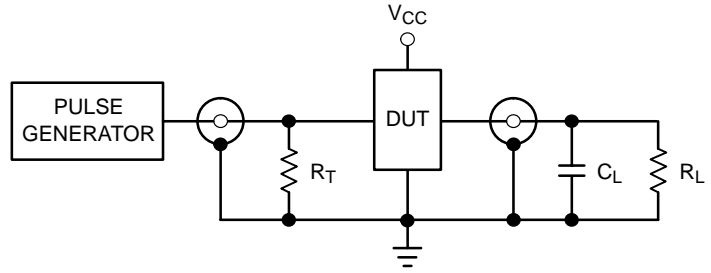
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### PROPAGATION DELAYS

$t_R = t_F = 2.5 \text{ ns}$ , 10% to 90%;  $f = 1 \text{ MHz}$ ;  $t_W = 500 \text{ ns}$

Figure 3. Switching Waveforms



$R_T = Z_{OUT}$  of pulse generator (typically  $50 \Omega$ )

Figure 4. Test Circuit

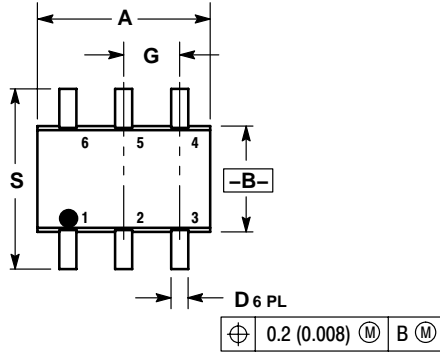
## DEVICE ORDERING INFORMATION

Device Order Number	Device Nomenclature							Package Type (Name/SOT#/Common Name)	Tape and Reel Size
	Logic Circuit Indicator	No. of Gates per Package	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape & Reel Suffix		
NL27WZ16DFT2	NL	2	7	WZ	16	DF	T2	SC-88 / SOT-363 / SC-70	178 mm (7") 3000 Unit
NL27WZ16DTT1	NL	2	7	WZ	16	DT	T1	TSOP-6 / SOT-23 / SC-59	178 mm (7") 3000 Unit

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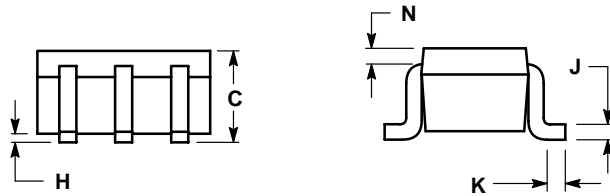
## PACKAGE DIMENSIONS

SC70-6/SC-88/SOT-363  
 DF SUFFIX  
 CASE 419B-02  
 ISSUE U

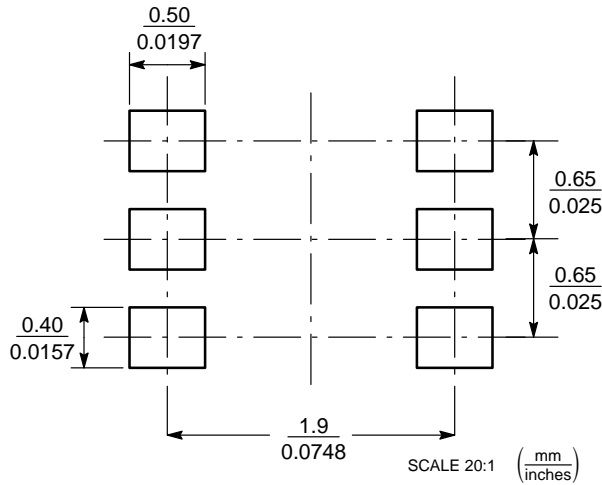


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20



### SOLDERING FOOTPRINT\*

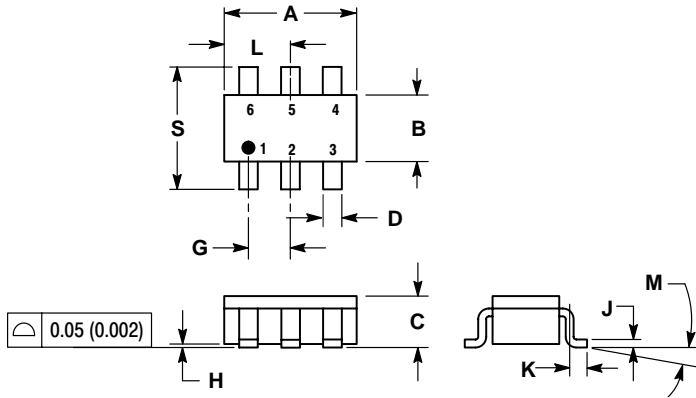


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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## PACKAGE DIMENSIONS

SOT23-6/TSOP-6/SC59-6  
DT SUFFIX  
CASE 318G-02  
ISSUE L

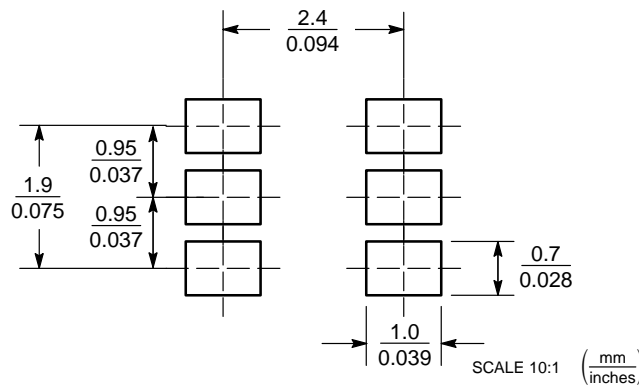


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.1142	0.1220
B	1.30	1.70	0.0512	0.0669
C	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.05	0.0335	0.0413
H	0.013	0.100	0.0005	0.0040
J	0.10	0.26	0.0040	0.0102
K	0.20	0.60	0.0079	0.0236
L	1.25	1.55	0.0493	0.0610
M	0°	10°	0°	10°
S	2.50	3.00	0.0985	0.1181

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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